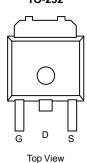


RoHS COMPLIANT

APM4034NU-VB Datasheet N-Channel 40-V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A) ^{a, e}	Q _g (Typ)		
40	0.012 at V _{GS} = 10 V	55	42 nC		
40	0.014 at V_{GS} = 4.5 V	45	42 110		



TO-252

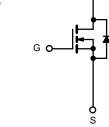
FEATURES

- TrenchFET[®] Power MOSFET
- 100 % R_g and UIS Tested
 Compliant to RoHS Directive 2011/65/EU

D

APPLICATIONS

- OR-ing •
- Server
- DC/DC •



N-Channel MOSFET

ABSOLUTE MAXIMUM RATING	S (T _A = 25 °C, unle	ess otherwise n	oted)	
Parameter		Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	40	V	
Gate-Source Voltage		V _{GS}	± 20	v
	T _C = 25 °C		55 ^{a, e}	
Continuous Drain Current (T $= 175$ °C)	T _C = 70 °C		45 ^e	
Continuous Drain Current (T _J = 175 °C)	T _A = 25 °C	I _D	15.8 ^{b, c}	A
	T _A = 70 °C		12 ^{b, c}	
Pulsed Drain Current	I _{DM} 20	200		
Avalanche Current Pulse	L = 0.1 mH	I _{AS}	39	
Single Pulse Avalanche Energy		E _{AS}	94.8	mJ
Continuous Source-Drain Diode Current	T _C = 25 °C	I _S	90 ^{a, e}	Α
Continuous Source-Drain Diode Current	T _A = 25 °C	'S	3.13 ^{b, c}	A
	T _C = 25 °C		100 ^a	
Maniatura Dania Diasia atian	T _C = 70 °C	Р	75	10/
Maximum Power Dissipation	T _A = 25 °C	PD	3.75 ^{b, c}	- W
	T _A = 70 °C		2.63 ^{b, c}	
Operating Junction and Storage Temperature R	T _J , T _{stg}	- 55 to 175	°C	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Тур.	Max.	Unit	
Maximum Junction-to-Ambient ^{b, d}	$t \le 10 \text{ sec}$	R _{thJA}	32	40	°C/W	
Maximum Junction-to-Case	Steady State	R _{thJC}	0.5	0.6	0/10	

Notes:

d. Maximum under steady state conditions is 90 °C/W.

e. Calculated based on maximum junction temperature. Package limitation current is 90 A.

a. Based on $T_C = 25$ °C. b. Surface mounted on 1" x 1" FR4 board. c. t = 10 sec.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static	1 - 1						
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, \text{ I}_{D} = 250 \mu\text{A}$ 44				V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	1 250 4		35			
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA		- 7.5		mV/°C	
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$	1.5		2.5	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
		$V_{DS} = 40 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			1		
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 40 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 \text{ °C}$			10	μA	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	90			А	
		V _{GS} = 10 V, I _D = 38.8 A		0.012		Ω	
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 37 \text{ A}$		0.014			
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 38.8 A		160		S	
Dynamic ^b	- 1 1			•			
Input Capacitance	C _{iss}			1801			
Output Capacitance	C _{oss}	V_{DS} = 15 V, V_{GS} = 0 V, f = 1 MHz		725		pF	
Reverse Transfer Capacitance	C _{rss}			570			
Total Gate Charge	0	V_{DS} = 15 V, V_{GS} = 10 V, I_{D} = 38.8 A		85	120	nC	
	Qg			42	62		
Gate-Source Charge	Q _{gs}	V_{DS} = 15 V, V_{GS} = 4.5 V, I_{D} = 28.8 A		17			
Gate-Drain Charge	Q _{gd}			14			
Gate Resistance	R _g	f = 1 MHz		1.4	2.1	Ω	
Turn-On Delay Time	t _{d(on)}			10	20		
Rise Time	t _r	V_{DD} = 15 V, R_L = 0.625 Ω		11	17]	
Turn-Off Delay Time	t _{d(off)}	$I_D \cong$ 24 A, V_{GEN} = 10 V, R_g = 1 Ω		35	55		
Fall Time	t _f			10	15		
Turn-On Delay Time	t _{d(on)}			25	43	ns	
Rise Time	t _r	V_{DD} = 15 V, R_L = 0.67 Ω		80	150	-	
Turn-Off Delay Time	t _{d(off)}	$\text{I}_\text{D}\cong\text{22.5}$ A, V_GEN = 4.5 V, R_g = 1 Ω		26	42		
Fall Time	t _f			12	18		
Drain-Source Body Diode Characteristic	cs						
Continuous Source-Drain Diode Current	۱ _S	$T_{C} = 25 \ ^{\circ}C$			120	A	
Pulse Diode Forward Current ^a	I _{SM}				120		
Body Diode Voltage	V_{SD}	I _S = 22 A		0.8	1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			52	78	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	I _F = 20 A, di/dt = 100 A/μs, T _J = 25 °C		70.2	105	nC	
Reverse Recovery Fall Time	t _a	$r_F = 20 \text{ A}, \text{ al/at} = 100 \text{ A/}\text{µs}, r_J = 25 \text{ °C}$		27			
Reverse Recovery Rise Time	t _b			25		ns	

Notes:

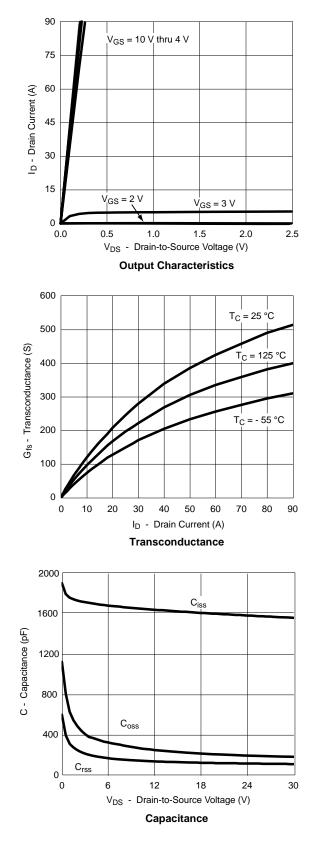
a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle ≤ 2 %.

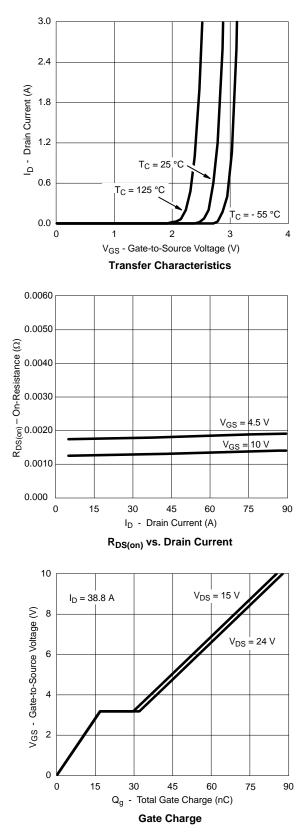
b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



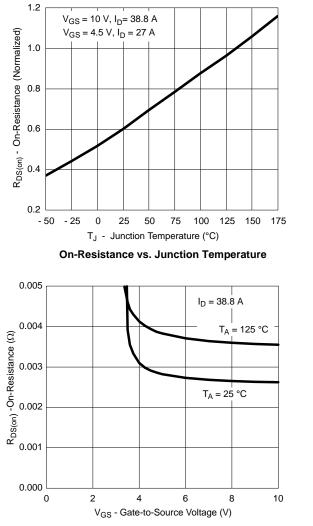




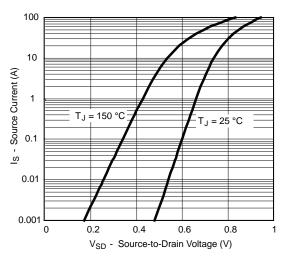






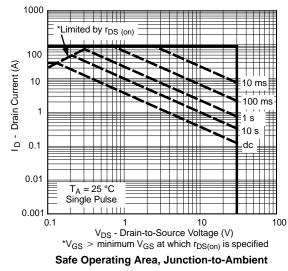


R_{DS(on)} vs. V_{GS} vs. Temperature

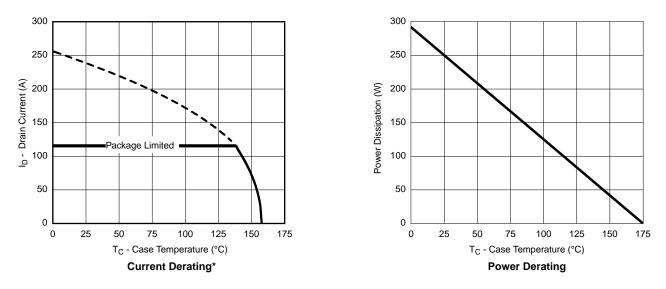






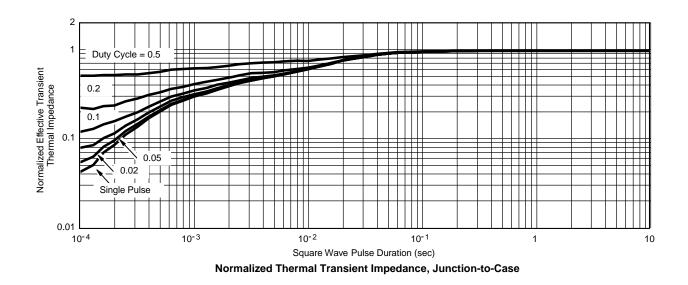






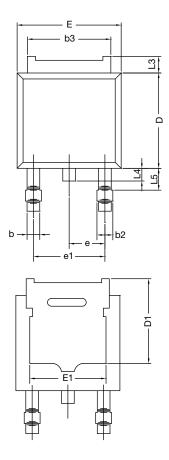
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

*The power dissipation P_D is based on $T_{J(max)} = 175$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.





TO-252AA CASE OUTLINE





	MILLIN	IETERS	INC	INCHES	
DIM.	MIN.	MAX.	MIN.	MAX.	
А	2.18	2.38	0.086	0.094	
A1	-	0.127	-	0.005	
b	0.64	0.88	0.025	0.035	
b2	0.76	1.14	0.030	0.045	
b3	4.95	5.46	0.195	0.215	
С	0.46	0.61	0.018	0.024	
C2	0.46	0.89	0.018	0.035	
D	5.97	6.22	0.235	0.245	
D1	5.21	-	0.205	-	
Е	6.35	6.73	0.250	0.265	
E1	4.32	-	0.170	-	
Н	9.40	10.41	0.370	0.410	
е	2.28 BSC		0.090 BSC		
e1	4.56 BSC		0.180 BSC		
L	1.40	1.78	0.055	0.070	
L3	0.89	1.27	0.035	0.050	
L4	-	1.02	-	0.040	
L5	1.14	1.52	0.045	0.060	
ECN: X12- DWG: 534	0247-Rev. M, 7	24-Dec-12			

Note

• Dimension L3 is for reference only.



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